

SOT1780-3

WLCSP36, wafer level chip-size package; 36 terminals; 0.4 mm pitch; 2.674 mm x 2.822 mm x 0.564 mm body

25 March 2020

Package information

1 Package summary

| | |
|--------------------------------|---------------------------------------|
| Terminal position code | B (bottom) |
| Package type descriptive code | WLCSP36 |
| Package style descriptive code | WLCSP (wafer level chip-size package) |
| Mounting method type | S (surface mount) |
| Issue date | 15-04-2016 |
| Manufacturer package code | 98ASA00949 |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-------|-------|-------|------|
| package length | 2.797 | 2.822 | 2.847 | mm |
| package width | 2.649 | 2.674 | 2.699 | mm |
| package height | - | 0.564 | 0.599 | mm |
| nominal pitch | - | 0.4 | - | mm |
| actual quantity of termination | - | 36 | - | |



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2 Package outline

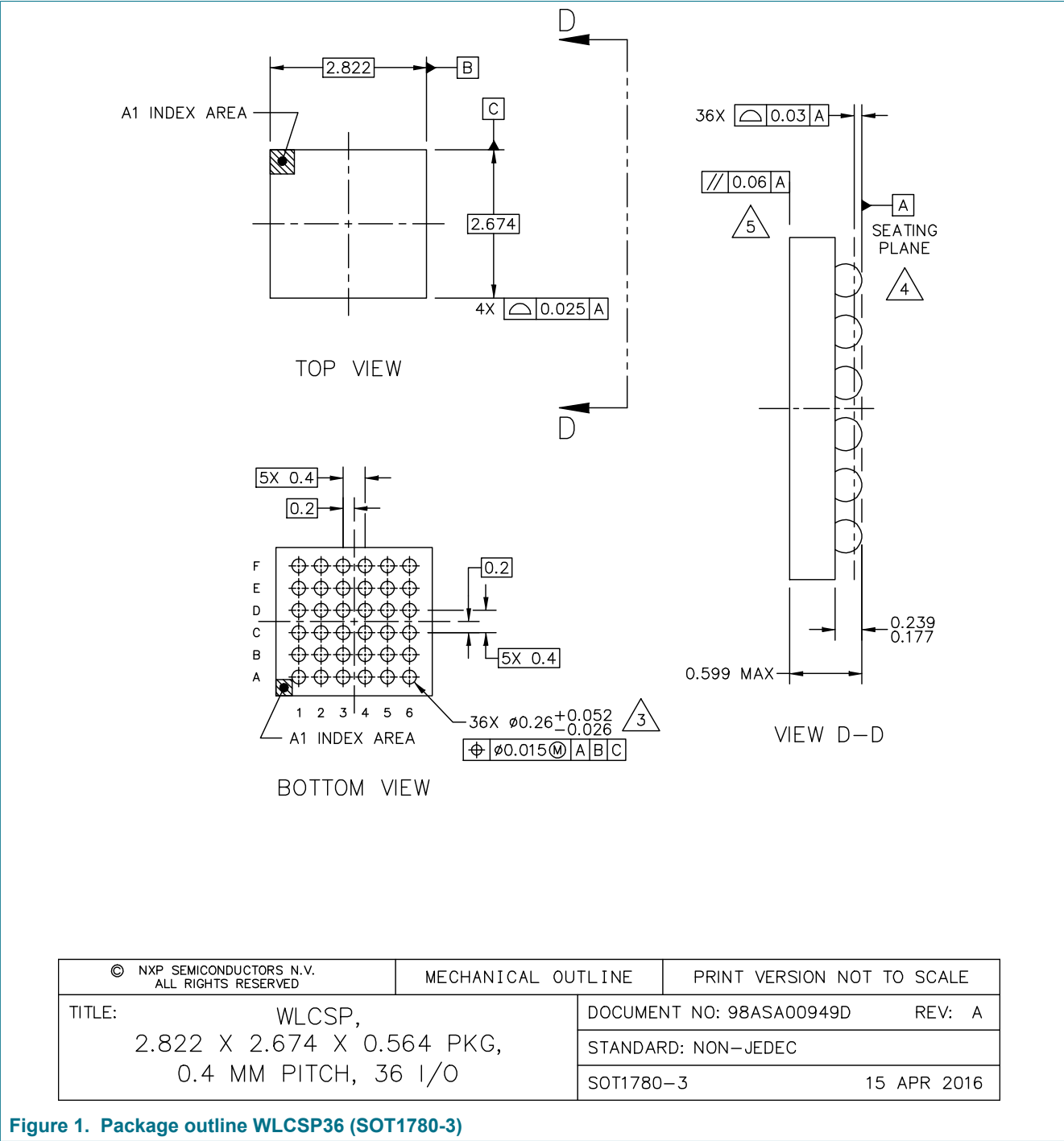


Figure 1. Package outline WLCSP36 (SOT1780-3)

WLCSP36, wafer level chip-size package; 36 terminals; 0.4 mm pitch; 2.674 mm x 2.822 mm x 0.564 mm body

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
 - 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

| | | |
|--|--------------------------------------|----------------------------|
| © NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED | MECHANICAL OUTLINE | PRINT VERSION NOT TO SCALE |
| TITLE: WLCSP, 2.822 X 2.674 X 0.564 PKG, 0.4 MM PITCH, 36 I/O | DOCUMENT NO: 98ASA00949D REV: A | |
| | STANDARD: NON-JEDEC | |
| | SOT1780-3 | 15 APR 2016 |

Figure 2. Package outline note WLCSP36 (SOT1780-3)

3 Legal information

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body

Contents

| | | |
|---|-------------------------|---|
| 1 | Package summary | 1 |
| 2 | Package outline | 2 |
| 3 | Legal information | 4 |